

TMX CT05

SAW Filter datasheet

3.0 x 3.0 x 1.3 mm, SMD

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TMX CT05

SAW Bandpass Filters | Wireless Communications

Features

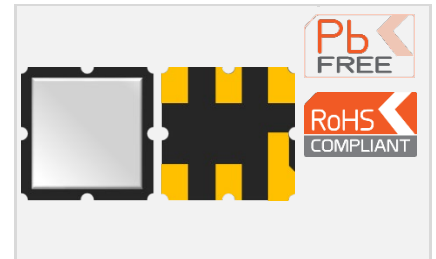
Features

- 866.5 MHz center frequency
- Ceramic package for Surface Mounted Technology
- Low-loss RF SAW Filter
- Wide Passband Width ± 3.5 MHz
- Low amplitude ripple
- 50 Ω Single Configuration. No matching network required

Applications

- Remote control - RF
- Wireless applications:
 - Home appliances
 - Security systems

3.0 x 3.0 x 1.3 mm



Maximum Ratings

Parameter	Min.	Typ.	Max.	Unit
Storage temperature range (T_{stg})	-45		125	$^{\circ}\text{C}$
Operating temperature range (T_A)	-40		125	$^{\circ}\text{C}$
ESD Voltage (HB)			150	V
DC permissive voltage			12	V
Maximum RF Power			15	dBm

Frequency and Electrical Characteristics (Reference temperature @ 25 $^{\circ}\text{C}$)

Parameter	Min.	Typ. ¹	Max.	Unit
Center frequency (f_c)		866.5		MHz
Bandwidth (BW, passband width)	7.00			MHz
Insertion Loss (IL, 863.0 – 870.0 MHz)		2.4	3.2	dB
Amplitude ripple (863.0 – 870.0 MHz)		0.3	1.0	dB
Absolute Attenuation				dB
From DC to 800.0 MHz	52	57		
From 800.0 to 830.0 MHz	45	50		
From 830.0 to 850.0 MHz	30	35		
From 885.0 to 905.0 MHz	25	30		
From 905.0 to 1500 MHz	47	54		
From 1500 to 2000 MHz	40	45		
VSWR (863.0 – 870.0 MHz)		1.5	2.0	
Source impedance ² (Single ended)		50		Ω
Load impedance ² (Single ended)		50		Ω

¹ Typical values are nominal performances at room temperature

² No external matching is required

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Model Outline, Pin Connection and Marking

TOP VIEW

FRONT VIEW

BOTTOM VIEW

Marking	Note
Line 1	CT05 RakonXpress designation
Line 2	S225 S = Production Code 2 = Year 2022 25 = Week 25
Line 3	• AA • = Identify black dot AA = Internal code (Wafer Batch)

RECOMMENDED PAD LAYOUT

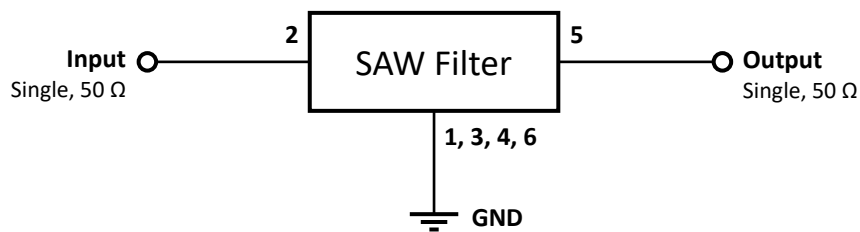
TOP VIEW

Pin	Connections
2	Input
5	Output
1, 3, 4, 6	Ground

Unit: mm

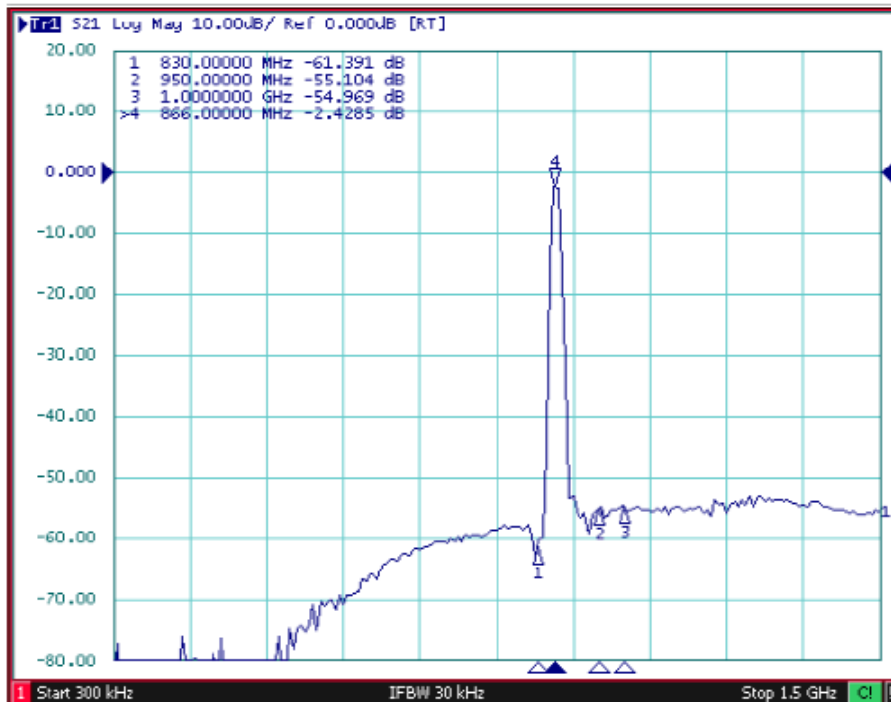
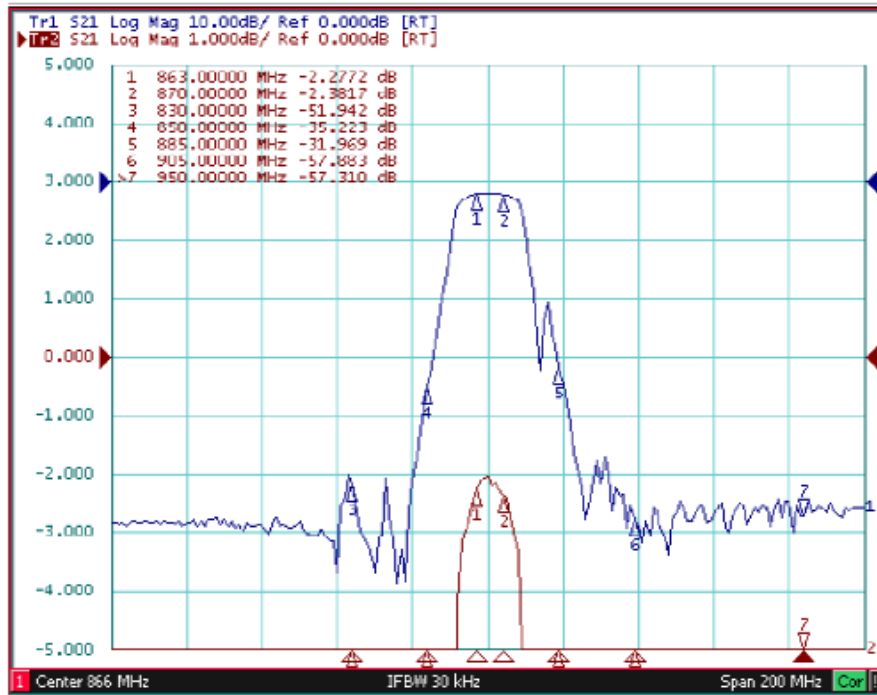
Test Circuit

50 Ω / 50 Ω Configuration

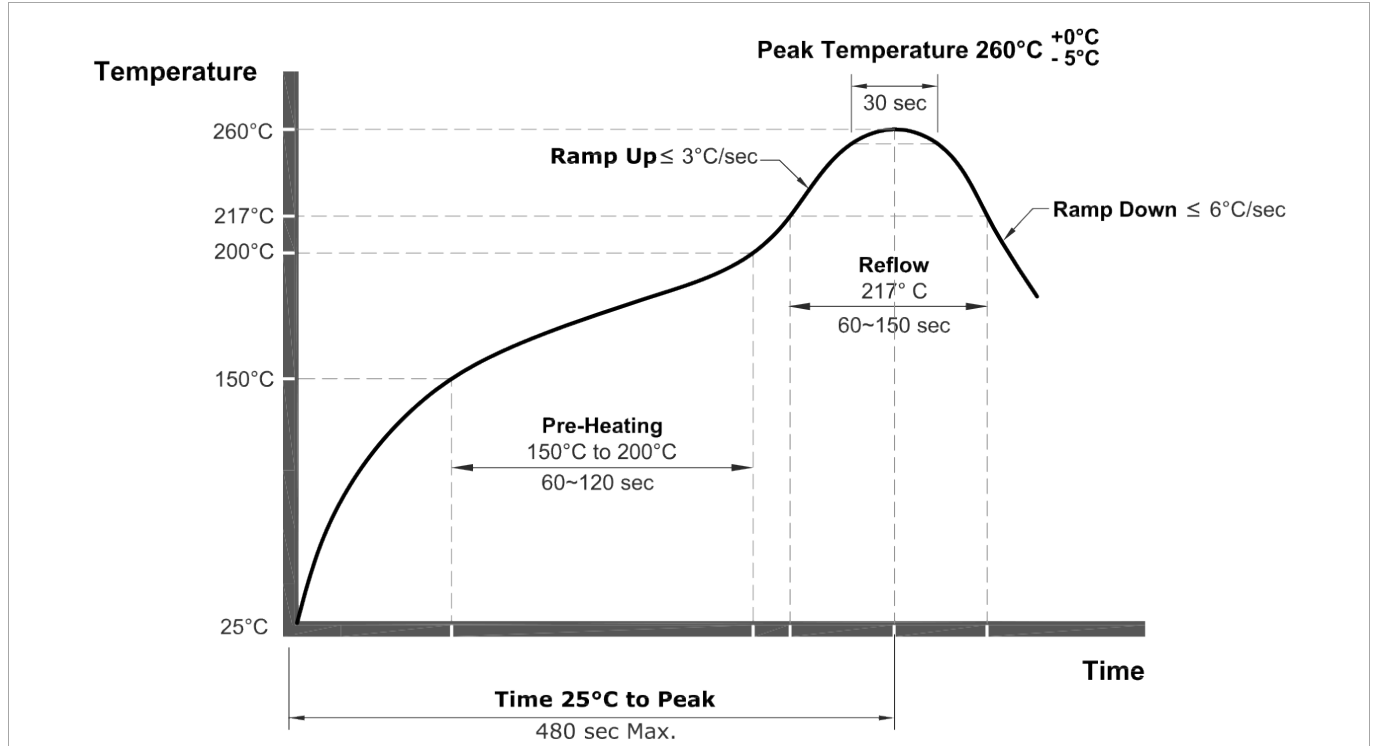


Frequency Characteristics

TYPICAL S21 RESPONSE



Recommended Reflow Soldering Profile



NOTE:

- The components shall remain within the electrical specifications after it soldered on the 1mm thickness PCB board and dipped in the solder at $260 \pm 5^\circ\text{C}$ during 10 ± 1 seconds.
- The components shall remain within the electrical specifications after it soldered by electric iron, solder at $350 \pm 10^\circ\text{C}$ during 3~4 seconds. Recovery time: 2 ± 0.5 hour.
- Ultrasonic cleaning may cause deterioration and destruction of the component. Please avoid ultrasonic cleaning.
- Only leads of components may be soldered. Please avoid soldering another part of the component.

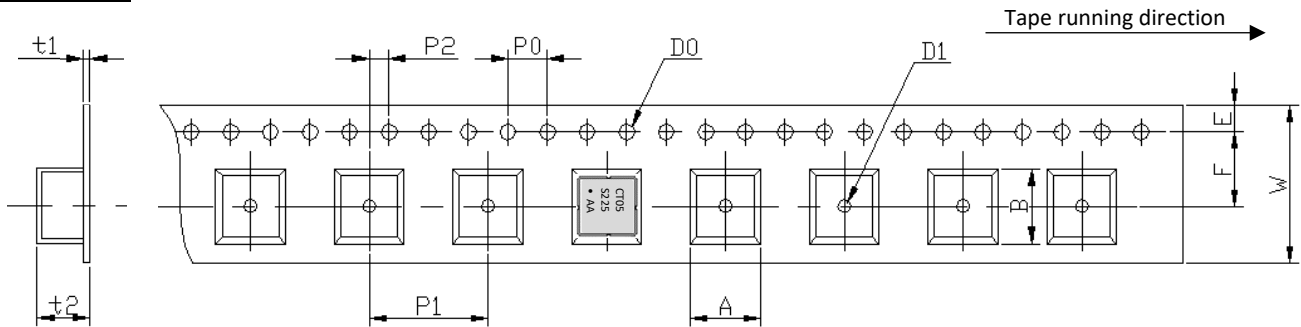
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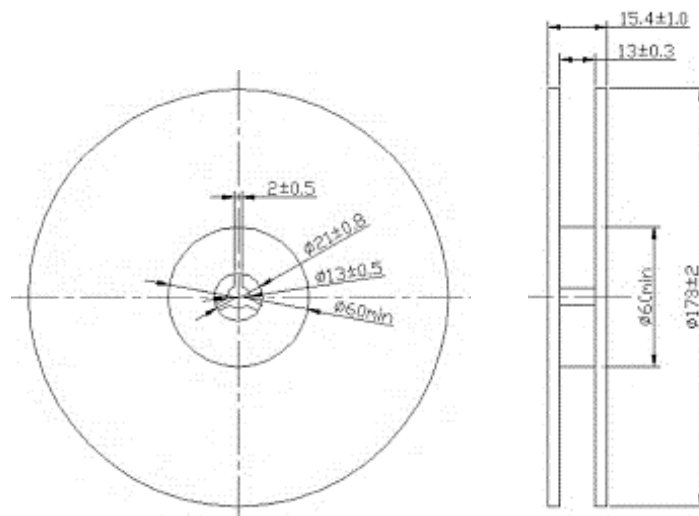
Tape and Reel Specifications

TAPE DETAILS:



Parameter	Code	Dimension	Tolerance
Height of component hole	A	3.3 max	
Width of component hole	B	3.3 max	
Diameter of sprocket hole	D ₀	Φ 1.5	± 0.1
Diameter of feed hole	D ₁	Φ 1.5	± 0.25
Pitch of sprocket hole	P ₀	4.0	± 0.1
Length from hole center to component center	P ₁	4.0	± 0.1
Length from Pocket hole center to sprocket hole center	P ₂	2.0	± 0.2
Width of carrier tape	W	12.0	± 0.3
Width of adhesive tape	F	5.5	± 0.3
Gap of hold down tape and carrier tape	E	1.75	± 0.1
Thickness of Embossed tape sheet	t ₁	0.31 max	
Thickness of Embossed tape	t ₂	1.7 max	

REEL DETAILS:



NOTE:

- Unit: mm
- Standard Packing Quantity (SPQ) is 3000 pieces/ reel

Reliability Test

Parameter	Test condition / Description
Thermal Shock	The components shall remain within the electrical specifications after being kept at the condition of heat cycle conditions: TA=-40° C ±3° C, TB=85° C ±2° C, t1=t2=30min, switch time ≤3min & cycle time: 100 times, recovery time: 2h ±0.5h.
Temperature Storage	High Temperature Storage: The components shall remain within the electrical specifications after being kept at the 85°C ±2°C for 500 hours, recovery time: 2h ±0.5h. Low Temperature Storage: The components shall remain within the electrical specifications after being kept at the -40°C ±3°C for 500 hours, recovery time: 2h ±0.5h.
Humidity test	The components shall remain within the electrical specifications after being kept at the condition of ambient temperature 60°C ±2°C, and 90~95% RH for 500 hours.
Drop test	The components shall remain within the electrical specifications after random free drops 10 times from height of 1.0 meter onto concrete floor, and the specimens shall meet the electrical specifications.
Vibration Fatigue	The components shall remain within the electrical specifications after loaded vibration at 10~55Hz, amplitude 1.5mm, X, Y, Z, direction, during 2 hours.
Mechanical Shock	The components shall remain within the electrical specifications after 1000 shocks, acceleration 392 m/s ² , duration 6ms.
Note	As a result of the particularity of inner structure of SAW products, the components can easily be breakdown by electrostatic shock; so it's mandatory to pay attention to ESD protect during the tests.